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Application No.: 10/755,042

JUL 2 0 2005

Docket No.: JCLA8533-D2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Mou-Shiung Lin et al.

Examiner

: FENTY, JESSE A.

Serial No. :

10/755,042

Art Unit

: 2815

Filed

January 9, 2004

Docket No.

: JCLA8533-D2

For

INTEGRATED CHIP PACKAGE

STRUCTURE USING SILICON

SUBSTRATE AND METHOD OF

MANUFACTURING THE SAME

the flyness entry 7/2/05

AMENDMENT AFTER FINAL

MAIL STOP AF Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The Office Action mailed April 20, 2005 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.